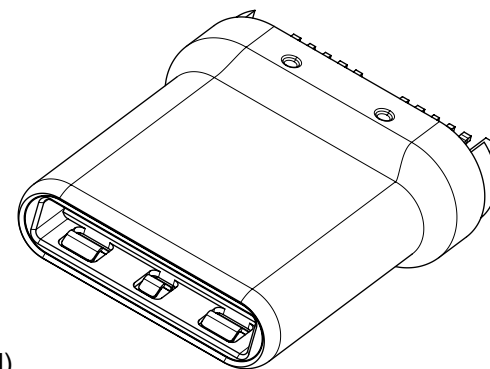


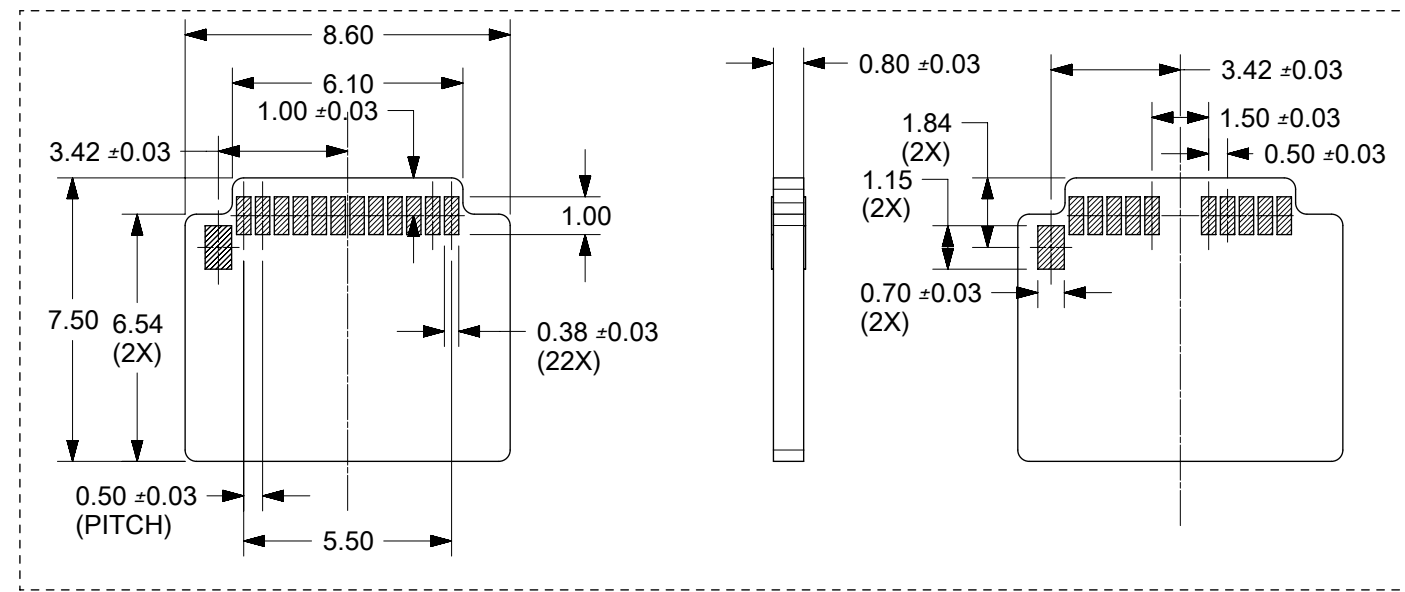
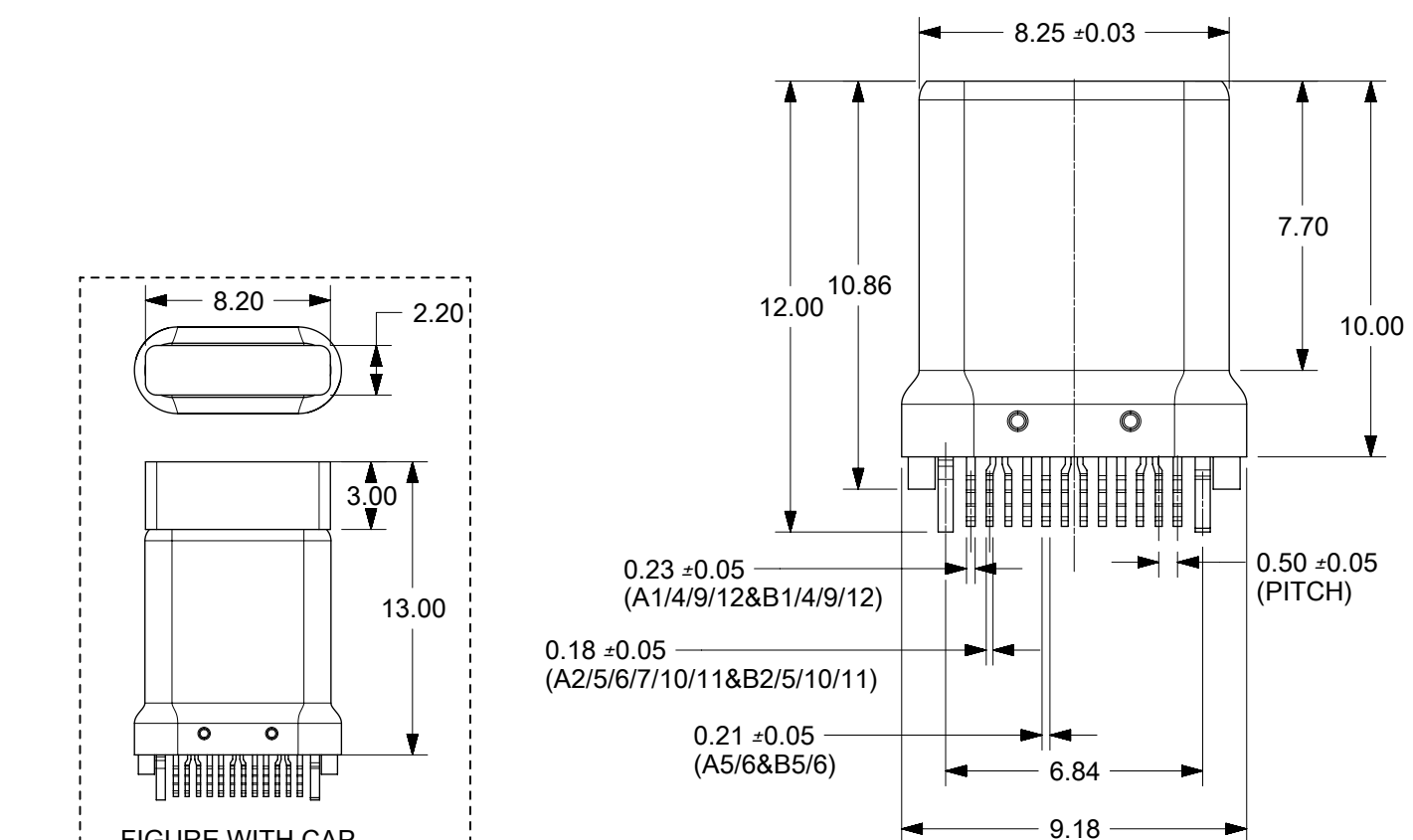
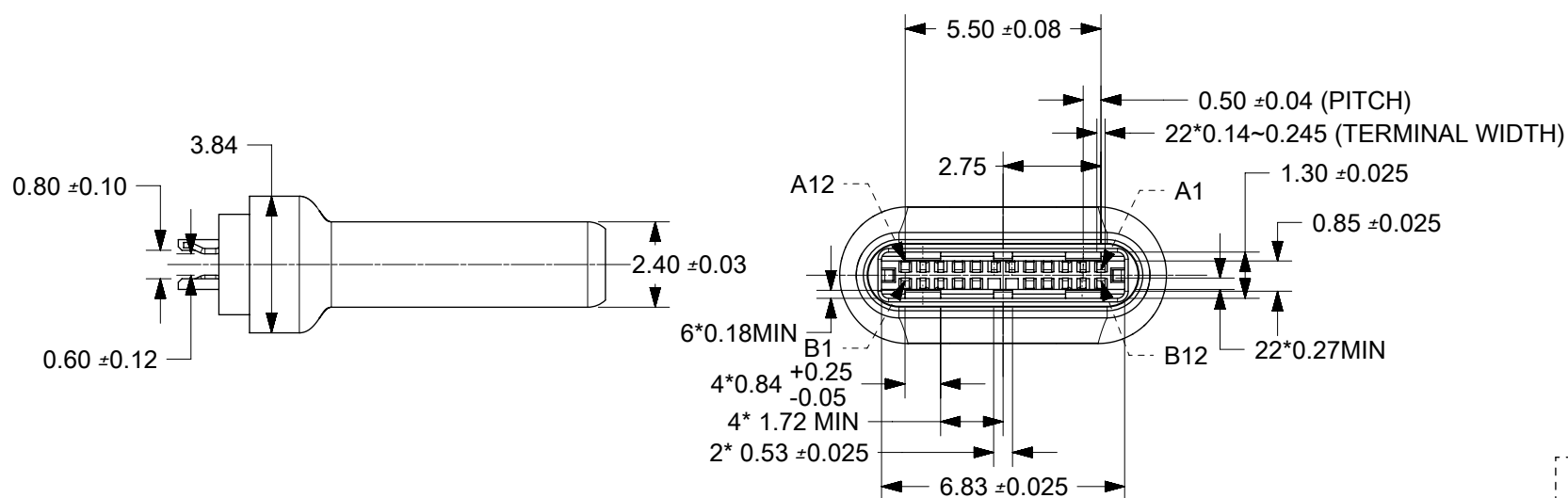
PIN ASSIGNMENT

A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1
GND	RX2+	RX2-	Vbus	Sbu1	D-	D+	CC	Vbus	TX1-	TX1+	GND
GND	TX2+	TX2-	Vbus	Vconn			Sbu2	VbuS	RX1-	RX1+	GND
B1	B2	B3	B4	B5			B8	B9	B10	B11	B12



NOTES:

- MATERIAL:
 - HOUSING: THERMOPLASTIC, UL94-V0; COLOR:BLACK;
 - INSERT MOLDING HOUSING: THERMOPLASTIC, UL94-V0;COLOR:BLACK;
 - TERMINAL: COPPER ALLOY;
 - OUTTER SHELL:STAINLESS STEEL;
 - FRONT SPRING::STAINLESS STEEL;
 - MIDDLE LATCH:STAINLESS STEEL;
 - ISOLATED LAYER:MYLAR;
- FINISH:
 - TERMINAL:
 - 80 MICROINCH MIN. NICKEL UNDERPLATING OVERALL,
 - 120 MICROINCH MIN. TIN PLATING ON SOLDERING AREA;;
 - PLEASE REFER TO TABLE FOR CONTACT AREA PLATING;
 - OUTTER SHELL:
 - 50 MICROINCH MIN. BRIGHT NICKEL UNDERPLATING OVERALL,
 - FRONT SPRING:
 - 50 MICROINCH MIN. NICKEL UNDERPLATING OVERALL;
 - MIDDLE LATCH:
 - 50 MICROINCH MIN. NICKEL UNDERPLATING OVERALL;
- PRODUCT SPECIFICATION:1054440001
- PACKAGE SPECIFICATION:1054440001



RECOMMENDED PCB LAYOUT
(DEFAULT TOLERANCE :+/-0.05)

PART NUMBER	PLATING ON TERMINAL CONTACT AREA
1054440001	30 MICROINCH MIN. GOLD PLATING
1054440101	GOLD FLASH OVER 30MICROINCH PbNi
1054440201	15 MICROINCH MIN. GOLD PLATING

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

RELEASED EC NO: 101909 DRWN: FYANG05 CHKD: REV	2015/11/25	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE		
	2015/12/01		MM	8:1		
			ANGULAR TOL ± 1.0 °	DRWN BY		DATE
			4 PLACES ±	FYANG05		2015/11/25
		3 PLACES ± 0.05	CHK'D BY	DATE	USB C PLUG,SPLINT PRODUCT CUSTOMER DRAWING	
		2 PLACES ± 0.25	APPR BY	DATE		
		1 PLACE ± 0.25	RZHANG	2015/12/01		
		0 PLACES ±	DRAWING SIZE	THIRD ANGLE PROJECTION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	B		SERIES: 105444 MATERIAL NUMBER: SEE TABLE CUSTOMER:	
					DOCUMENT NUMBER: 1054440001 DOC TYPE: PSD DOC PART: SM SHEET NUMBER: 1 OF 1	